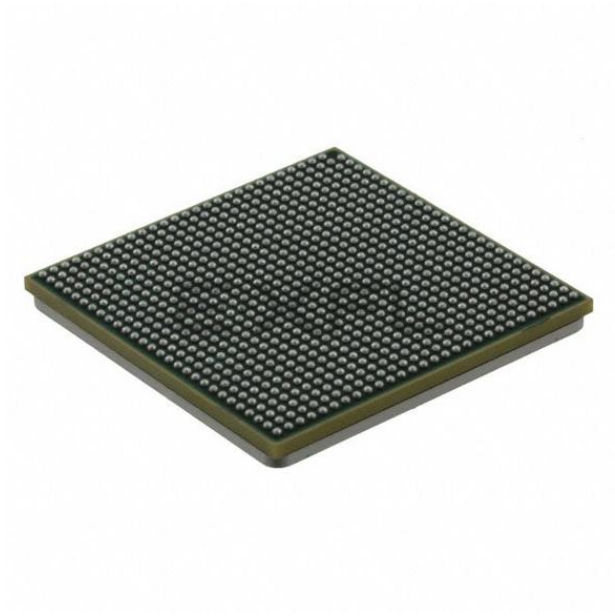

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	PowerPC e500v2
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	667MHz
Co-Processors/DSP	-
RAM Controllers	DDR, DDR2
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10/100/1000Mbps (2)
SATA	-
USB	-
Voltage - I/O	1.8V, 2.5V, 3.3V
Operating Temperature	0°C ~ 90°C (TA)
Security Features	-
Package / Case	783-BBGA, FCBGA
Supplier Device Package	783-FCPBGA (29x29)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mpc8533vtalfa

- Double-precision floating-point APU. Provides an instruction set for double-precision (64-bit) floating-point instructions that use the 64-bit GPRs.
- 36-bit real addressing
- Embedded vector and scalar single-precision floating-point APUs. Provide an instruction set for single-precision (32-bit) floating-point instructions.
- Memory management unit (MMU). Especially designed for embedded applications. Supports 4-Kbyte–4-Gbyte page sizes.
- Enhanced hardware and software debug support
- Performance monitor facility that is similar to, but separate from, the device performance monitor

The e500 defines features that are not implemented on this device. It also generally defines some features that this device implements more specifically. An understanding of these differences can be critical to ensure proper operations.

- 256-Kbyte L2 cache/SRAM
  - Flexible configuration
  - Full ECC support on 64-bit boundary in both cache and SRAM modes
  - Cache mode supports instruction caching, data caching, or both.
  - External masters can force data to be allocated into the cache through programmed memory ranges or special transaction types (stashing).
    - 1, 2, or 4 ways can be configured for stashing only.
  - Eight-way set-associative cache organization (32-byte cache lines)
  - Supports locking entire cache or selected lines. Individual line locks are set and cleared through Book E instructions or by externally mastered transactions.
  - Global locking and flash clearing done through writes to L2 configuration registers
  - Instruction and data locks can be flash cleared separately.
  - SRAM features include the following:
    - I/O devices access SRAM regions by marking transactions as snoopable (global).
    - Regions can reside at any aligned location in the memory map.
    - Byte-accessible ECC is protected using read-modify-write transaction accesses for smaller-than-cache-line accesses.
- Address translation and mapping unit (ATMU)
  - Eight local access windows define mapping within local 36-bit address space.
  - Inbound and outbound ATMUs map to larger external address spaces.
    - Three inbound windows plus a configuration window on PCI and PCI Express
    - Four outbound windows plus default translation for PCI and PCI Express
- DDR/DDR2 memory controller
  - Programmable timing supporting DDR and DDR2 SDRAM
  - 64-bit data interface

Figure 1 shows the MPC8533E block diagram.

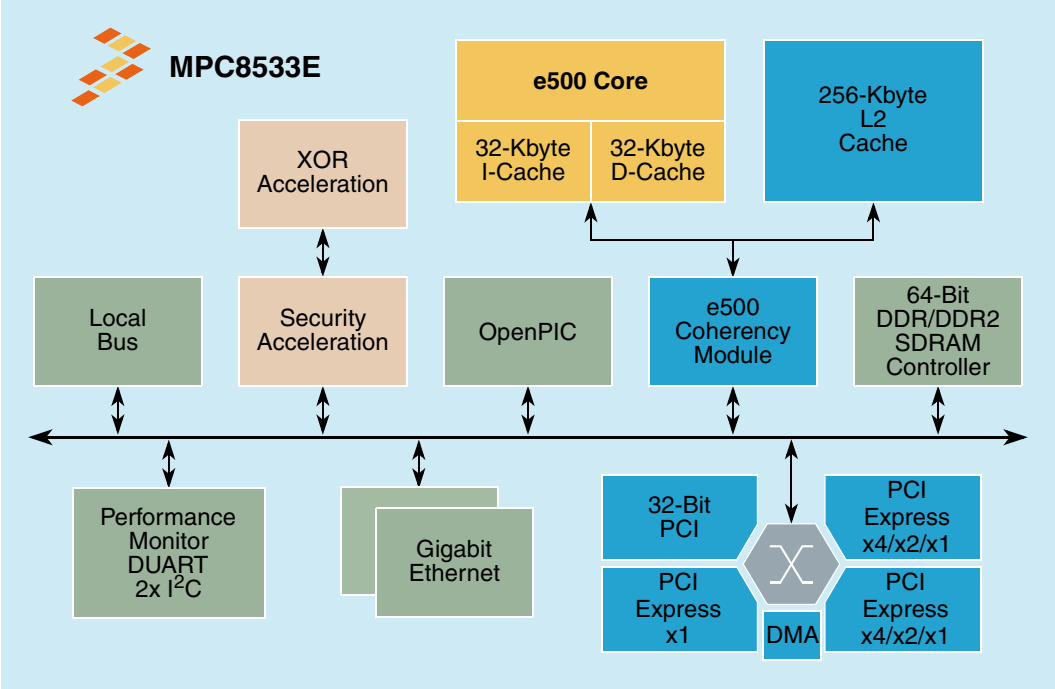


Figure 1. MPC8533E Block Diagram

2 Electrical Characteristics

This section provides the AC and DC electrical specifications and thermal characteristics for the MPC8533E. This device is currently targeted to these specifications. Some of these specifications are independent of the I/O cell, but are included for a more complete reference. These are not purely I/O buffer design specifications.

2.1 Overall DC Electrical Characteristics

This section covers the ratings, conditions, and other characteristics.

2.1.1 Absolute Maximum Ratings

Table 1 provides the absolute maximum ratings.

Table 1. Absolute Maximum Ratings[1]

Characteristic	Symbol	Max Value	Unit	Notes
Core supply voltage	V_{DD}	–0.3 to 1.1	V	—
PLL supply voltage	AV_{DD}	–0.3 to 1.1	V	—
Core power supply for SerDes transceivers	SV_{DD}	–0.3 to 1.1	V	—
Pad power supply for SerDes transceivers	XV_{DD}	–0.3 to 1.1	V	—

3 Power Characteristics

The estimated typical core power dissipation for the core complex bus (CCB) versus the core frequency for this family of PowerQUICC III devices is shown in Table 4.

Table 4. MPC8533E Core Power Dissipation

Power Mode	Core Frequency (MHz)	Platform Frequency (MHz)	V_{DD} (V)	Junction Temperature (°C)	Power (W)	Notes
Typical	667	333	1.0	65	2.6	1, 2
Thermal				90	3.75	1, 3
Maximum					5.85	1, 4
Typical	800	400	1.0	65	2.9	1, 2
Thermal				90	4.0	1, 3
Maximum					6.0	1, 4
Typical	1000	400	1.0	65	3.6	1, 2
Thermal				90	4.4	1, 3
Maximum					6.2	1, 4
Typical	1067	533	1.0	65	3.9	1, 2
Thermal				90	5.0	1, 3
Maximum					6.5	1, 4

Notes:

1. These values specify the power consumption at nominal voltage and apply to all valid processor bus frequencies and configurations. The values do not include power dissipation for I/O supplies.
2. Typical power is an average value measured at the nominal recommended core voltage (V_{DD}) and 65°C junction temperature (see Table 2) while running the Dhrystone 2.1 benchmark.
3. Thermal power is the average power measured at nominal core voltage (V_{DD}) and maximum operating junction temperature (see Table 2) while running the Dhrystone 2.1 benchmark.
4. Maximum power is the maximum power measured at nominal core voltage (V_{DD}) and maximum operating junction temperature (see Table 2) while running a smoke test which includes an entirely L1-cache-resident, contrived sequence of instructions which keep the execution unit maximally busy.

4 Input Clocks

This section contains the following subsections:

- Section 4.1, “System Clock Timing”
- Section 4.2, “Real-Time Clock Timing”
- Section 4.3, “eTSEC Gigabit Reference Clock Timing”
- Section 4.4, “Platform to FIFO Restrictions”
- Section 4.5, “Other Input Clocks”

Table 16 provides the input AC timing specifications for the DDR SDRAM when $GV_{DD}(typ) = 2.5$ V.

Table 16. DDR SDRAM Input AC Timing Specifications for 2.5-V Interface

At recommended operating conditions.

Parameter	Symbol	Min	Max	Unit	Notes
AC input low voltage	V_{IL}	—	$MV_{REF} - 0.31$	V	—
AC input high voltage	V_{IH}	$MV_{REF} + 0.31$	—	V	—

Table 17 provides the input AC timing specifications for the DDR SDRAM interface.

Table 17. DDR SDRAM Input AC Timing Specifications

At recommended operating conditions.

Parameter	Symbol	Min	Max	Unit	Notes
Controller skew for MDQS—MDQ/MECC/MDM	t_{CISKEW}			ps	1, 2
533 MHz		–300	300		3
400 MHz		–365	365		—
333 MHz		–390	390		—

Notes:

1. t_{CISKEW} represents the total amount of skew consumed by the controller between MDQS[n] and any corresponding bit that will be captured with MDQS[n]. This should be subtracted from the total timing budget.
2. The amount of skew that can be tolerated from MDQS to a corresponding MDQ signal is called t_{DISKEW}. This can be determined by the following equation: $t_{DISKEW} = \pm (T/4 - abs(t_{CISKEW}))$, where T is the clock period and $abs(t_{CISKEW})$ is the absolute value of t_{CISKEW}. See Figure 3.
3. Maximum DDR1 frequency is 400 MHz.

Figure 3 shows the DDR SDRAM input timing diagram.

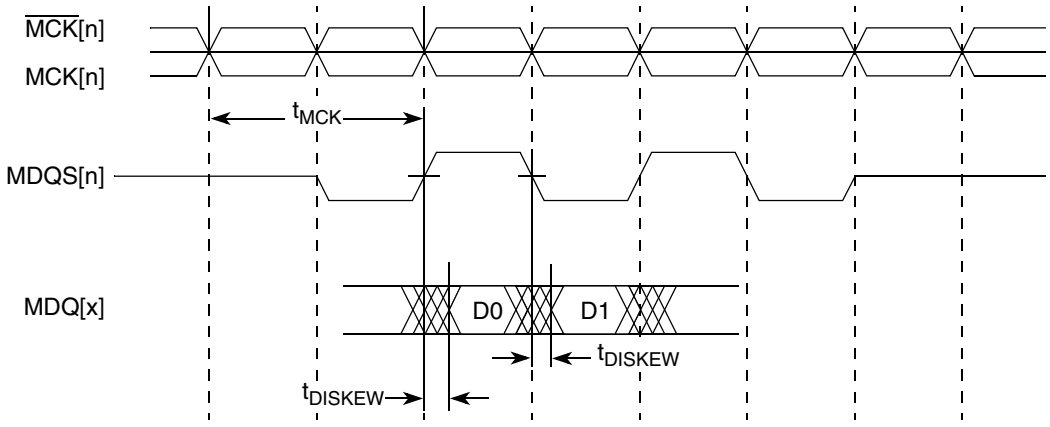


Figure 3. DDR SDRAM Input Timing Diagram (t_{DISKEW})

Table 18. DDR SDRAM Output AC Timing Specifications (continued)

At recommended operating conditions.

Parameter	Symbol[1]	Min	Max	Unit	Notes
MDQS postamble	t_{DDKHME}	0.4 x tMCK	0.6 x tMCK	ns	6

Notes:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. Output hold time can be read as DDR timing (DD) from the rising or falling edge of the reference clock (KH or KL) until the output went invalid (AX or DX). For example, t_{DDKHAS} symbolizes DDR timing (DD) for the time t_{MCK} memory clock reference (K) goes from the high (H) state until outputs (A) are setup (S) or output valid time. Also, t_{DDKLDX} symbolizes DDR timing (DD) for the time t_{MCK} memory clock reference (K) goes low (L) until data outputs (D) are invalid (X) or data output hold time.
2. All MCK/$\overline{\text{MCK}}$ referenced measurements are made from the crossing of the two signals ±0.1 V.
3. ADDR/CMD includes all DDR SDRAM output signals except MCK/$\overline{\text{MCK}}$, $\overline{\text{MCS}}$, and MDQ/MECC/MDM/MDQS.
4. Note that t_{DDKHMH} follows the symbol conventions described in note 1. For example, t_{DDKHMH} describes the DDR timing (DD) from the rising edge of the MCK[n] clock (KH) until the MDQS signal is valid (MH). t_{DDKHMH} can be modified through control of the DQSS override bits in the TIMING_CFG_2 register. This will typically be set to the same delay as the clock adjust in the CLK_CNTL register. The timing parameters listed in the table assume that these two parameters have been set to the same adjustment value. See the *MPC8533E PowerQUICC III Integrated Communications Processor Reference Manual,* for a description and understanding of the timing modifications enabled by use of these bits.
5. Determined by maximum possible skew between a data strobe (MDQS) and any corresponding bit of data (MDQ), ECC (MECC), or data mask (MDM). The data strobe should be centered inside of the data eye at the pins of the microprocessor.
6. All outputs are referenced to the rising edge of MCK[n] at the pins of the microprocessor. Note that t_{DDKHMP} follows the symbol conventions described in note 1.
7. Maximum DDR1 frequency is 400 MHz.

NOTE

For the ADDR/CMD setup and hold specifications in Table 18, it is assumed that the clock control register is set to adjust the memory clocks by ½ applied cycle.

Figure 4 shows the DDR SDRAM output timing for the MCK to MDQS skew measurement (t_{DDKHMH}).

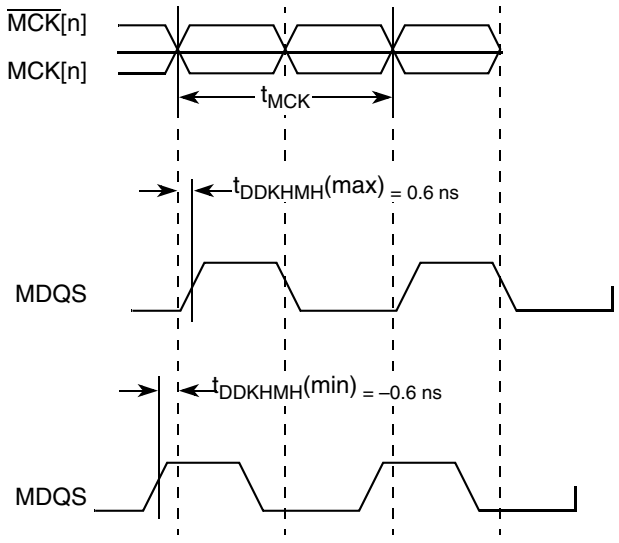


Figure 4. Timing Diagram for t_{DDKHMH}

8.5.1 TBI Transmit AC Timing Specifications

Table 29 provides the TBI transmit AC timing specifications.

Table 29. TBI Transmit AC Timing Specifications

At recommended operating conditions with L/TVDD of 3.3 V ± 5% or 2.5 V ± 5%

Parameter/Condition	Symbol[1]	Min	Typ	Max	Unit	Notes
GTX_CLK clock period	t_{GTX}	—	8.0	—	ns	—
GTX_CLK to TCG[9:0] delay time	t_{TTKHDX}	0.2	—	5.0	ns	2
GTX_CLK rise (20%–80%)	t_{TTXR}	—	—	1.0	ns	—
GTX_CLK fall time (80%–20%)	t_{TTXF}	—	—	1.0	ns	—

Notes:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{TTKHDV} symbolizes the TBI transmit timing (TT) with respect to the time from t_{TTX} (K) going high (H) until the referenced data signals (D) reach the valid state (V) or setup time. Also, t_{TTKHDX} symbolizes the TBI transmit timing (TT) with respect to the time from t_{TTX} (K) going high (H) until the referenced data signals (D) reach the invalid state (X) or hold time. Note that, in general, the clock reference symbol representation is based on three letters representing the clock of a particular functional. For example, the subscript of t_{TTX} represents the TBI (T) transmit (TX) clock. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall).
2. Data valid t_{TTKHDV} to GTX_CLK Min setup time is a function of clock period and max hold time (Min setup = cycle time – Max delay).

Figure 15 shows the TBI transmit AC timing diagram.

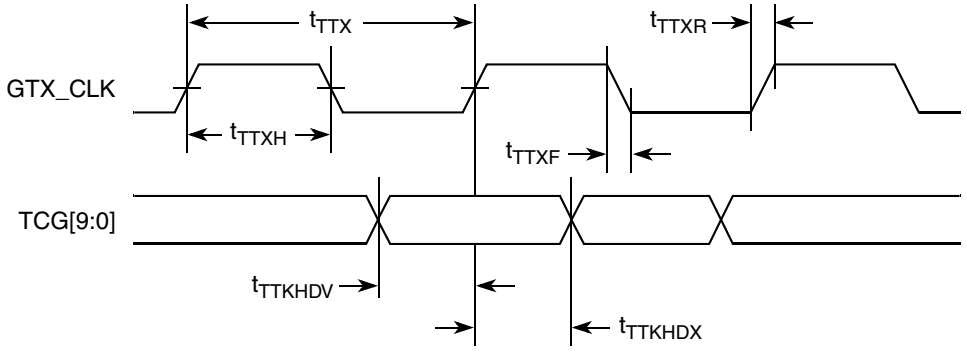


Figure 15. TBI Transmit AC Timing Diagram

8.5.2 TBI Receive AC Timing Specifications

Table 30 provides the TBI receive AC timing specifications.

Table 30. TBI Receive AC Timing Specifications

At recommended operating conditions with L/TVDD of 3.3 V ± 5% or 2.5 V ± 5%.

Parameter/Condition	Symbol[1]	Min	Typ	Max	Unit	Notes
PMA_RX_CLK[0:1] clock period	t_{TRX}	—	16.0	—	ns	—
PMA_RX_CLK[0:1] skew	t_{SKTRX}	7.5	—	8.5	ns	—

8.5.5 RMII AC Timing Specifications

This section describes the RMII transmit and receive AC timing specifications.

8.5.5.1 RMII Transmit AC Timing Specifications

The RMII transmit AC timing specifications are in Table 33.

Table 33. RMII Transmit AC Timing Specifications

At recommended operating conditions with L/TV_{DD} of 3.3 V ± 5% or 2.5 V ± 5%.

Parameter/Condition	Symbol[1]	Min	Typ	Max	Unit	Notes
REF_CLK clock period	t_{RMT}	15.0	20.0	25.0	ns	—
REF_CLK duty cycle	t_{RMTH}	35	50	65	%	—
REF_CLK peak-to-peak jitter	t_{RMTJ}	—	—	250	ps	—
Rise time REF_CLK (20%–80%)	t_{RMTR}	1.0	—	2.0	ns	—
Fall time REF_CLK (80%–20%)	t_{RMTF}	1.0	—	2.0	ns	—
REF_CLK to RMII data TXD[1:0], TX_EN delay	t_{RMTDX}	1.0	—	10.0	ns	—

Note:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{MTKHDX} symbolizes MII transmit timing (MT) for the time t_{MTX} clock reference (K) going high (H) until data outputs (D) are invalid (X). Note that, in general, the clock reference symbol representation is based on two to three letters representing the clock of a particular functional. For example, the subscript of t_{MTX} represents the MII(M) transmit (TX) clock. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall).

Figure 19 shows the RMII transmit AC timing diagram.

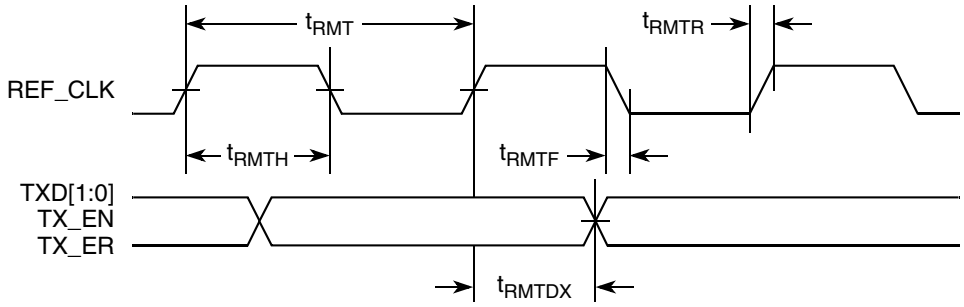


Figure 19. RMII Transmit AC Timing Diagram

8.5.5.2 RMII Receive AC Timing Specifications

Table 34 shows the RMII receive AC timing specifications.

Table 34. RMII Receive AC Timing Specifications

At recommended operating conditions with LV_{DD} of 3.3 V ± 5%.or 2.5 V ± 5%.

Parameter/Condition	Symbol[1]	Min	Typ	Max	Unit	Notes
REF_CLK clock period	t_{RMR}	15.0	20.0	25.0	ns	—
REF_CLK duty cycle	t_{RMRH}	35	50	65	%	—
REF_CLK peak-to-peak jitter	t_{RMRJ}	—	—	250	ps	—
Rise time REF_CLK (20%–80%)	t_{RMRR}	1.0	—	2.0	ns	—
Fall time REF_CLK (80%–20%)	t_{RMRF}	1.0	—	2.0	ns	—
RXD[1:0], CRS_DV, RX_ER setup time to REF_CLK rising edge	t_{RMRDV}	4.0	—	—	ns	—
RXD[1:0], CRS_DV, RX_ER hold time to REF_CLK rising edge	t_{RMRDX}	2.0	—	—	ns	—

Note:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{MRDVKH} symbolizes MII receive timing (MR) with respect to the time data input signals (D) reach the valid state (V) relative to the t_{MRX} clock reference (K) going to the high (H) state or setup time. Also, t_{MRDXKL} symbolizes MII receive timing (GR) with respect to the time data input signals (D) went invalid (X) relative to the t_{MRX} clock reference (K) going to the low (L) state or hold time. Note that, in general, the clock reference symbol representation is based on three letters representing the clock of a particular functional. For example, the subscript of t_{MRX} represents the MII (M) receive (RX) clock. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall).

Figure 20 provides the AC test load for eTSEC.

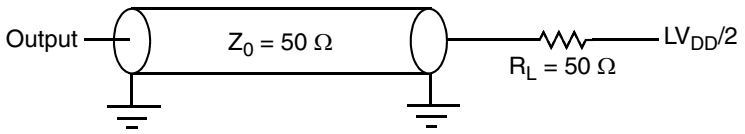


Figure 20. eTSEC AC Test Load

Figure 21 shows the RMII receive AC timing diagram.

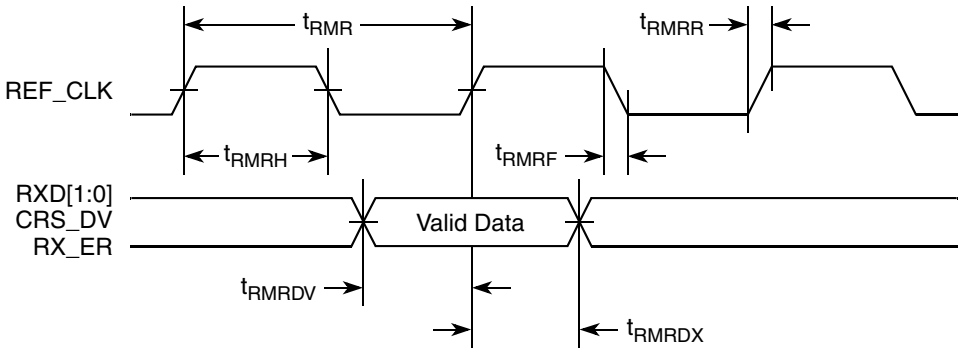


Figure 21. RMII Receive AC Timing Diagram

15.2 PCI AC Electrical Specifications

This section describes the general AC timing parameters of the PCI bus. Note that the SYSCLK signal is used as the PCI input clock. Table 51 provides the PCI AC timing specifications at 66 MHz.

Table 51. PCI AC Timing Specifications at 66 MHz

Parameter	Symbol[1]	Min	Max	Unit	Notes
SYSCLK to output valid	t_{PCKHOV}	—	7.4	ns	2, 3
Output hold from SYSCLK	t_{PCKHOX}	2.0	—	ns	2
SYSCLK to output high impedance	t_{PCKHOZ}	—	14	ns	2, 4
Input setup to SYSCLK	t_{PCIVKH}	3.7	—	ns	2, 5
Input hold from SYSCLK	t_{PCIXKH}	0.5	—	ns	2, 5
$\overline{\text{REQ64}}$ to $\overline{\text{HRESET}}$[9] setup time	t_{PCRVRH}	$10 \times t_{SYS}$	—	clocks	6, 7
$\overline{\text{HRESET}}$ to $\overline{\text{REQ64}}$ hold time	t_{PCRHRX}	0	50	ns	7
$\overline{\text{HRESET}}$ high to first $\overline{\text{FRAME}}$ assertion	t_{PCRHFV}	10	—	clocks	8
Rise time (20%–80%)	t_{PCICLK}	0.6	2.1	ns	—
Fall time (20%–80%)	t_{PCICLK}	0.6	2.1	ns	—

Notes:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{PCIVKH} symbolizes PCI timing (PC) with respect to the time the input signals (I) reach the valid state (V) relative to the SYSCLK clock, t_{SYS}, reference (K) going to the high (H) state or setup time. Also, t_{PCRHFV} symbolizes PCI timing (PC) with respect to the time hard reset (R) went high (H) relative to the frame signal (F) going to the valid (V) state.
2. See the timing measurement conditions in the *PCI 2.2 Local Bus Specifications*.
3. All PCI signals are measured from $OV_{DD}/2$ of the rising edge of PCI_SYNC_IN to $0.4 \times OV_{DD}$ of the signal in question for 3.3-V PCI signaling levels.
4. For purposes of active/float timing measurements, the Hi-Z or off state is defined to be when the total current delivered through the component pin is less than or equal to the leakage current specification.
5. Input timings are measured at the pin.
6. The timing parameter t_{SYS} indicates the minimum and maximum CLK cycle times for the various specified frequencies. The system clock period must be kept within the minimum and maximum defined ranges. For values see Section 19, “Clocking.”
7. The setup and hold time is with respect to the rising edge of $\overline{\text{HRESET}}$.
8. The timing parameter t_{PCRHFV} is a minimum of 10 clocks rather than the minimum of 5 clocks in the *PCI 2.2 Local Bus Specifications*.
9. The reset assertion timing requirement for $\overline{\text{HRESET}}$ is 100 μs.

Figure 37 provides the AC test load for PCI.

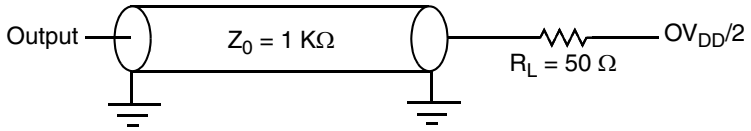


Figure 37. PCI AC Test Load

assumes that the LVPECL clock driver's output impedance is 50 Ω. R1 is used to DC-bias the LVPECL outputs prior to AC-coupling. Its value could be ranged from 140 to 240 Ω depending on clock driver vendor's requirement. R2 is used together with the SerDes reference clock receiver's 50-Ω termination resistor to attenuate the LVPECL output's differential peak level such that it meets the MPC8533E SerDes reference clock's differential input amplitude requirement (between 200 and 800 mV differential peak). For example, if the LVPECL output's differential peak is 900 mV and the desired SerDes reference clock input amplitude is selected as 600 mV, the attenuation factor is 0.67, which requires R2 = 25 Ω. Please consult clock driver chip manufacturer to verify whether this connection scheme is compatible with a particular clock driver chip.

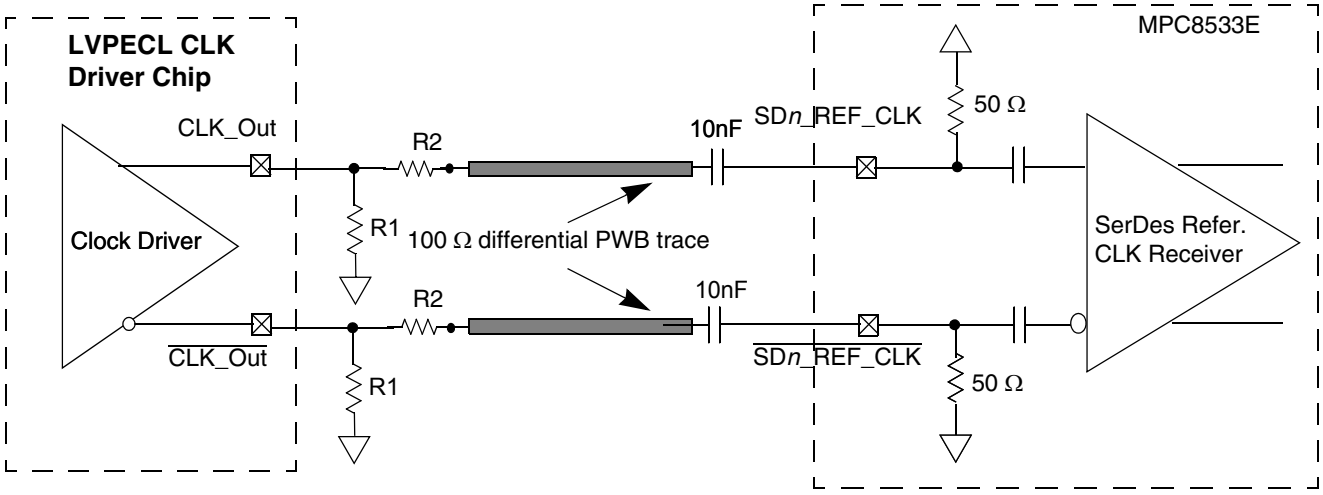


Figure 47. AC-Coupled Differential Connection with LVPECL Clock Driver (Reference Only)

Figure 48 shows the SerDes reference clock connection reference circuits for a single-ended clock driver. It assumes the DC levels of the clock driver are compatible with MPC8533E SerDes reference clock input's DC requirement.

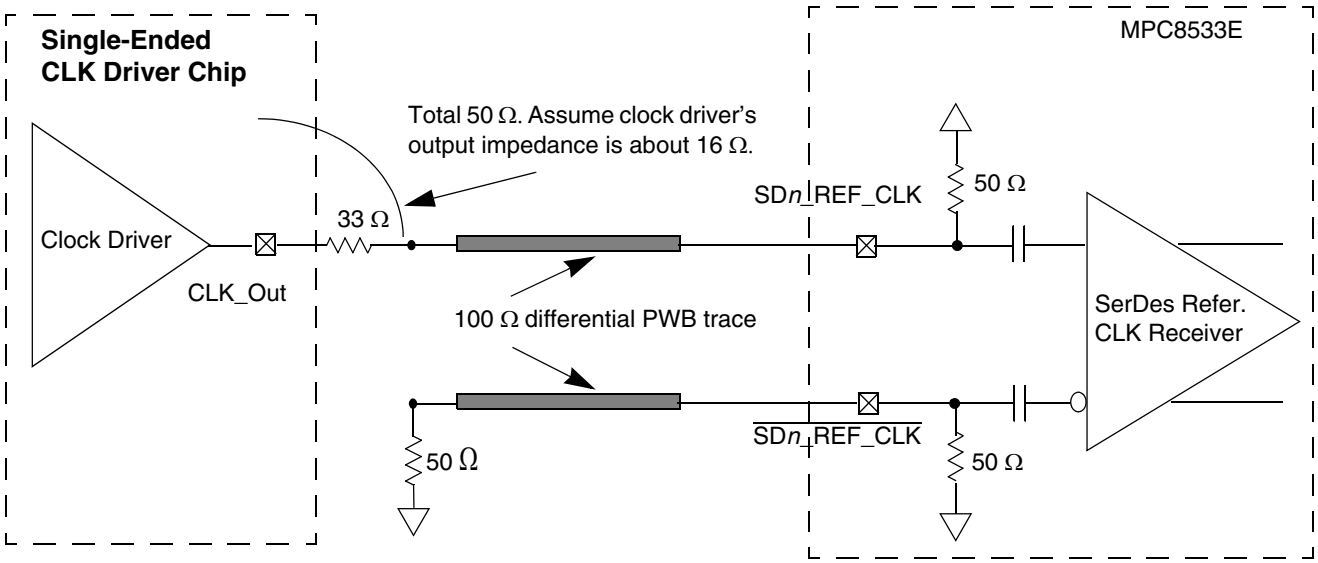


Figure 48. Single-Ended Connection (Reference Only)

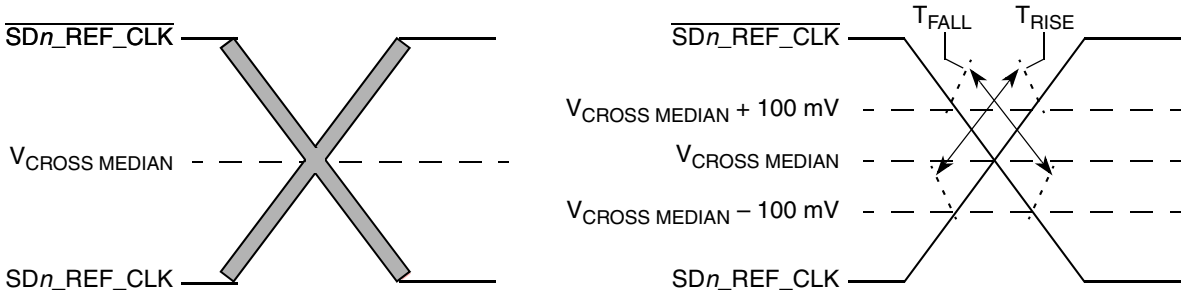


Figure 50. Single-Ended Measurement Points for Rise and Fall Time Matching

The other detailed AC requirements of the SerDes reference clocks is defined by each interface protocol based on application usage. Refer to the following sections for detailed information:

- Section 17.2, "AC Requirements for PCI Express SerDes Clocks"

16.2.4.1 Spread Spectrum Clock

SD1_REF_CLK/$\overline{\text{SD1\_REF\_CLK}}$ were designed to work with a spread spectrum clock (+0 to –0.5% spreading at 30–33 kHz rate is allowed), assuming both ends have same reference clock. For better results, a source without significant unintended modulation should be used.

SD2_REF_CLK/$\overline{\text{SD2\_REF\_CLK}}$ are not intended to be used with, and should not be clocked by, a spread spectrum clock source.

16.3 SerDes Transmitter and Receiver Reference Circuits

Figure 51 shows the reference circuits for SerDes data lane's transmitter and receiver.

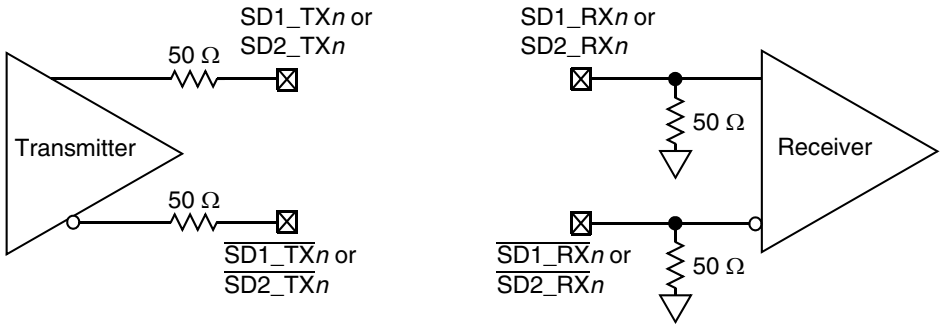


Figure 51. SerDes Transmitter and Receiver Reference Circuits

The DC and AC specification of SerDes data lanes are defined in the section below (PCI Express) in this document based on the application usage:

- Section 17, "PCI Express"

Please note that external AC Coupling capacitor is required for the above serial transmission protocols with the capacitor value defined in specification of each protocol section.

Table 55. Differential Receiver (RX) Input Specifications (continued)

Symbol	Parameter	Min	Nom	Max	Units	Comments
$L_{TX-SKEW}$	Total skew	—	—	20	ns	Skew across all lanes on a link. This includes variation in the length of SKP ordered set (for example, COM and one to five symbols) at the RX as well as any delay differences arising from the interconnect itself.

Notes:
1. No test load is necessarily associated with this value.
2. Specified at the measurement point and measured over any 250 consecutive UIs. The test load in Figure 54 should be used as the RX device when taking measurements (also refer to the receiver compliance eye diagram shown in Figure 53). If the clocks to the RX and TX are not derived from the same reference clock, the TX UI recovered from 3500 consecutive UI must be used as a reference for the eye diagram.
3. A T_{RX-EYE} = 0.40 UI provides for a total sum of 0.60 UI deterministic and random jitter budget for the transmitter and interconnect collected any 250 consecutive UIs. The TRX-EYE-MEDIAN-to-MAX-JITTER specification ensures a jitter distribution in which the median and the maximum deviation from the median is less than half of the total. UI jitter budget collected over any 250 consecutive TX UIs. It should be noted that the median is not the same as the mean. The jitter median describes the point in time where the number of jitter points on either side is approximately equal as opposed to the averaged time value. If the clocks to the RX and TX are not derived from the same reference clock, the TX UI recovered from 3500 consecutive UI must be used as the reference for the eye diagram.
4. The receiver input impedance shall result in a differential return loss greater than or equal to 15 dB with the D+ line biased to 300 mV and the D– line biased to –300 mV and a common mode return loss greater than or equal to 6 dB (no bias required) over a frequency range of 50 MHz to 1.25 GHz. This input impedance requirement applies to all valid input levels. The reference impedance for return loss measurements for is 50 Ω to ground for both the D+ and D– line (that is, as measured by a vector network analyzer with 50-Ω probes, see Figure 54). Note that the series capacitors CTX is optional for the return loss measurement.
5. Impedance during all LTSSM states. When transitioning from a fundamental reset to detect (the initial state of the LTSSM) there is a 5-ms transition time before receiver termination values must be met on all unconfigured lanes of a port.
6. The RX DC common mode impedance that exists when no power is present or fundamental reset is asserted. This helps ensure that the receiver detect circuit will not falsely assume a receiver is powered on when it is not. This term must be measured at 300 mV above the RX ground.
7. It is recommended that the recovered TX UI is calculated using all edges in the 3500 consecutive UI interval with a fit algorithm using a minimization merit function. Least squares and median deviation fits have worked well with experimental and simulated data.

17.5 Receiver Compliance Eye Diagrams

The RX eye diagram in Figure 53 is specified using the passive compliance/test measurement load (see Figure 54) in place of any real PCI Express RX component.

In general, the minimum receiver eye diagram measured with the compliance/test measurement load (see Figure 54) will be larger than the minimum receiver eye diagram measured over a range of systems at the input receiver of any real PCI Express component. The degraded eye diagram at the input receiver is due to traces internal to the package as well as silicon parasitic characteristics which cause the real PCI Express component to vary in impedance from the compliance/test measurement load. The input receiver eye diagram is implementation specific and is not specified. RX component designer should provide additional margin to adequately compensate for the degraded minimum receiver eye diagram (shown in Figure 53) expected at the input receiver based on some adequate combination of system simulations and the return loss measured looking into the RX package and silicon. The RX eye diagram must be aligned in time using the jitter median to locate the center of the eye diagram.

18.3 Pinout Listings

Table 57 provides the pinout listing for the MPC8533E 783 FC-PBGA package.

NOTE

The naming convention of TSEC1 and TSEC3 is used to allow the splitting voltage rails for the eTSEC blocks and to ease the port of existing PowerQUICC III software.

NOTE

The $\overline{\text{DMA\_DACK}}$[0:1] and $\overline{\text{TEST\_SEL}}$ pins must be set to a proper state during POR configuration. Please refer to Table 57 for more details.

Table 57. MPC8533E Pinout Listing

Signal	Package Pin Number	Pin Type	Power Supply	Notes
PCI				
PCI1_AD[31:0]	AE8, AD8, AF8, AH12, AG12, AB9, AC9, AE9, AD10, AE10, AC11, AB11, AB12, AC12, AF12, AE11, Y14, AE15, AC15, AB15, AA15, AD16, Y15, AB16, AF18, AE18, AC17, AE19, AD19, AB17, AB18, AA16	I/O	OV_{DD}	—
PCI1_C_$\overline{\text{BE}}$[3:0]	AC10, AE12, AA14, AD17	I/O	OV_{DD}	—
$\overline{\text{PCI1\_GNT}}$[4:1]	AE7, AG11,AH11, AC8	O	OV_{DD}	4, 8, 24
$\overline{\text{PCI1\_GNT0}}$	AE6	I/O	OV_{DD}	—
$\overline{\text{PCI1\_IRDY}}$	AF13	I/O	OV_{DD}	2
PCI1_PAR	AB14	I/O	OV_{DD}	—
$\overline{\text{PCI1\_PERR}}$	AE14	I/O	OV_{DD}	2
$\overline{\text{PCI1\_SERR}}$	AC14	I/O	OV_{DD}	2
$\overline{\text{PCI1\_STOP}}$	AA13	I/O	OV_{DD}	2
$\overline{\text{PCI1\_TRDY}}$	AD13	I/O	OV_{DD}	2
$\overline{\text{PCI1\_REQ}}$[4:1]	AF9, AG10, AH10, AD6	I	OV_{DD}	—
$\overline{\text{PCI1\_REQ0}}$	AB8	I/O	OV_{DD}	—
PCI1_CLK	AH26	I	OV_{DD}	—
$\overline{\text{PCI1\_DEVSEL}}$	AC13	I/O	OV_{DD}	2
$\overline{\text{PCI1\_FRAME}}$	AD12	I/O	OV_{DD}	2
PCI1_IDSEL	AG6	I	OV_{DD}	—

Table 57. MPC8533E Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
DDR SDRAM Memory Interface				
MDQ[0:63]	A26, B26, C22, D21, D25, B25, D22, E21, A24, A23, B20, A20, A25, B24, B21, A21, E19, D19, E16, C16, F19, F18, F17, D16, B18, A18, A15, B14, B19, A19, A16, B15, D1, F3, G1, H2, E4, G5, H3, J4, B2, C3, F2, G2, A2, B3, E1, F1, L5, L4,N3, P3, J3, K4, N4, P4, J1, K1, P1, R1, J2, K2, N1, R2	I/O	GV_{DD}	—
MECC[0:7]	G12, D14, F11, C11, G14, F14,C13, D12	I/O	GV_{DD}	—
MDM[0:8]	C25, B23, D18, B17, G4, C2, L3, L2, F13	O	GV_{DD}	21
$\overline{\text{MDQS}}$[0:8]	D24, B22, C18, A17, J5, C1, M4, M2, E13	I/O	GV_{DD}	—
MDQS[0:8]	C23, A22, E17, B16, K5, D2, M3, P2, D13	I/O	GV_{DD}	—
MA[0:15]	B7, G8, C8, A10, D9, C10, A11, F9, E9, B12, A5, A12, D11, F7, E10, F10	O	GV_{DD}	—
MBA[0:2]	A4, B5, B13	O	GV_{DD}	—
$\overline{\text{MWE}}$	B4	O	GV_{DD}	—
$\overline{\text{MCAS}}$	E7	O	GV_{DD}	—
$\overline{\text{MRAS}}$	C5	O	GV_{DD}	—
MCKE[0:3]	H10, K10, G10, H9	O	GV_{DD}	10
$\overline{\text{MCS}}$[0:3]	D3, H6, C4, G6	O	GV_{DD}	—
MCK[0:5]	A9, J11, J6, A8, J13, H8	O	GV_{DD}	—
$\overline{\text{MCK}}$[0:5]	B9, H11, K6, B8, H13, J8	O	GV_{DD}	—
MODT[0:3]	E5, H7, E6, F6	O	GV_{DD}	—
MDIC[0:1]	H15, K15	I/O	GV_{DD}	25
TEST_IN	A13	I	—	27
TEST_OUT	A6	O	—	17
Local Bus Controller Interface				
LAD[0:31]	K22, L21, L22, K23, K24, L24, L25, K25, L28, L27, K28, K27, J28, H28, H27, G27, G26, F28, F26, F25, E28, E27, E26, F24, E24, C26, G24, E23, G23, F22, G22, G21	I/O	BV_{DD}	23
LDP[0:3]	K26, G28, B27, E25	I/O	BV_{DD}	
LA[27]	L19	O	BV_{DD}	4, 8
LA[28:31]	K16, K17, H17,G17	O	BV_{DD}	4, 6, 8
$\overline{\text{LCS}}$[0:4]	K18, G19, H19, H20, G16	O	BV_{DD}	—
$\overline{\text{LCS5}}$/$\overline{\text{DMA\_DREQ2}}$	H16	I/O	BV_{DD}	1

Table 57. MPC8533E Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
LCS6/DMA_DACK2	J16	O	BV_{DD}	1
LCS7/DMA_DDONE2	L18	O	BV_{DD}	1
LWE0/LBS0/LSDDQM[0]	J22	O	BV_{DD}	4, 8
LWE1/LBS1/LSDDQM[1]	H22	O	BV_{DD}	4, 8
LWE2/LBS2/LSDDQM[2]	H23	O	BV_{DD}	4, 8
LWE3/LBS3/LSDDQM[3]	H21	O	BV_{DD}	4, 8
LALE	J26	O	BV_{DD}	4, 7, 8
LBCTL	J25	O	BV_{DD}	4, 7, 8
LGPL0/LSDA10	J20	O	BV_{DD}	4, 8
LGPL1/LSDWE	K20	O	BV_{DD}	4, 8
LGPL2/LOE/LSDRAS	G20	O	BV_{DD}	4, 7, 8
LGPL3/LSDCAS	H18	O	BV_{DD}	4, 8
LGPL4/LGTA/LUPWAIT/ LPBSE	L20	I/O	BV_{DD}	28
LGPL5	K19	O	BV_{DD}	4, 8
LCKE	L17	O	BV_{DD}	—
LCLK[0:2]	H24, J24, H25	O	BV_{DD}	—
LSYNC_IN	D27	I	BV_{DD}	—
LSYNC_OUT	D28	O	BV_{DD}	—
DMA				
DMA_DACK[0:1]	Y13, Y12	O	OV_{DD}	4, 8, 9
DMA_DREQ[0:1]	AA10, AA11	I	OV_{DD}	—
DMA_DDONE[0:1]	AA7, Y11	O	OV_{DD}	—
Programmable Interrupt Controller				
UDE	AH15	I	OV_{DD}	—
MCP	AG18	I	OV_{DD}	—
IRQ[0:7]	AG22, AF17, AD21, AF19, AG17, AF16, AC23, AC22	I	OV_{DD}	—
IRQ[8]	AC19	I	OV_{DD}	—
IRQ[9]/DMA_DREQ3	AG20	I	OV_{DD}	1
IRQ[10]/DMA_DACK3	AE27	I/O	OV_{DD}	1
IRQ[11]/DMA_DDONE3	AE24	I/O	OV_{DD}	1
IRQ_OUT	AD14	O	OV_{DD}	2

Table 57. MPC8533E Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
Ethernet Management Interface				
EC_MDC	AC7	O	OV_{DD}	4, 8, 14
EC_MDIO	Y9	I/O	OV_{DD}	—
Gigabit Reference Clock				
EC_GTX_CLK125	T2	I	LV_{DD}	—
Three-Speed Ethernet Controller (Gigabit Ethernet 1)				
TSEC1_RXD[7:0]	U10, U9, T10, T9, U8, T8, T7, T6	I	LV_{DD}	—
TSEC1_TXD[7:0]	T5, U5, V5, V3, V2, V1, U2, U1	O	LV_{DD}	4, 8, 14
TSEC1_COL	R5	I	LV_{DD}	—
TSEC1_CRS	T4	I/O	LV_{DD}	16
TSEC1_GTX_CLK	T1	O	LV_{DD}	—
TSEC1_RX_CLK	V7	I	LV_{DD}	—
TSEC1_RX_DV	U7	I	LV_{DD}	—
TSEC1_RX_ER	R9	I	LV_{DD}	4, 8
TSEC1_TX_CLK	V6	I	LV_{DD}	—
TSEC1_TX_EN	U4	O	LV_{DD}	22
TSEC1_TX_ER	T3	O	LV_{DD}	—
Three-Speed Ethernet Controller (Gigabit Ethernet 3)				
TSEC3_RXD[7:0]	P11, N11, M11, L11, R8, N10, N9, P10	I	LV_{DD}	—
TSEC3_TXD[7:0]	M7, N7, P7, M8, L7, R6, P6, M6	O	LV_{DD}	4, 8, 14
TSEC3_COL	M9	I	LV_{DD}	—
TSEC3_CRS	L9	I/O	LV_{DD}	16
TSEC3_GTX_CLK	R7	O	LV_{DD}	—
TSEC3_RX_CLK	P9	I	LV_{DD}	—
TSEC3_RX_DV	P8	I	LV_{DD}	—
TSEC3_RX_ER	R11	I	LV_{DD}	—
TSEC3_TX_CLK	L10	I	LV_{DD}	—
TSEC3_TX_EN	N6	O	LV_{DD}	22
TSEC3_TX_ER	L8	O	LV_{DD}	4, 8
DUART				
$\overline{\text{UART\_CTS}}$[0:1]	AH8, AF6	I	OV_{DD}	—
$\overline{\text{UART\_RTS}}$[0:1]	AG8, AG9	O	OV_{DD}	—

Table 57. MPC8533E Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
SD2_REF_CLK	AF2	I	XV_{DD}	—
SD2_TST_CLK	AG4	—	—	—
SD2_TST_CLK	AF4	—	—	—
General-Purpose Output				
GPOUT[0:7]	AF22, AH23, AG27, AH25, AF21, AF25, AG26, AF26	O	OV_{DD}	—
General-Purpose Input				
GPIN[0:7]	AH24, AG24, AD23, AE21, AD22, AF23, AG25, AE20	I	OV_{DD}	—
System Control				
HRESET	AG16	I	OV_{DD}	—
HRESET_REQ	AG15	O	OV_{DD}	21
SRESET	AG19	I	OV_{DD}	—
CKSTP_IN	AH5	I	OV_{DD}	—
CKSTP_OUT	AA12	O	OV_{DD}	2, 4
Debug				
TRIG_IN	AC5	I	OV_{DD}	—
TRIG_OUT/READY/ QUIESCE	AB5	O	OV_{DD}	5, 8, 15, 21
MSRCID[0:1]	Y7, W9	O	OV_{DD}	4, 5, 8
MSRCID[2:4]	AA9, AB6, AD5	O	OV_{DD}	5, 15, 21
MDVAL	Y8	O	OV_{DD}	5
CLK_OUT	AE16	O	OV_{DD}	10
Clock				
RTC	AF15	I	OV_{DD}	—
SYSCLK	AH16	I	OV_{DD}	—
JTAG				
TCK	AG28	I	OV_{DD}	—
TDI	AH28	I	OV_{DD}	11
TDO	AF28	O	OV_{DD}	10
TMS	AH27	I	OV_{DD}	11
TRST	AH22	I	OV_{DD}	11

Table 57. MPC8533E Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes

6.The value of LA[28:31] during reset sets the CCB clock to SYSCLK PLL ratio. These pins require 4.7-kΩ pull-up or pull-down resistors. See Section 19.2, "CCB/SYSCLK PLL Ratio."
7.The value of LALE, LGPL2, and LBCTL at reset set the e500 core clock to CCB clock PLL ratio. These pins require 4.7-kΩ pull-up or pull-down resistors. See Section 19.3, "e500 Core PLL Ratio."
8.Functionally, this pin is an output, but structurally it is an I/O because it either samples configuration input during reset or because it has other manufacturing test functions. Therefore, this pin will be described as an I/O for boundary scan.
9.For proper state of these signals during reset, these pins can be left without any pull downs, thus relying on the internal pullup to get the values to the require 2'b11. However, if there is any device on the net which might pull down the value of the net at reset, then a pullup is needed.
10.This output is actively driven during reset rather than being three-stated during reset.
11.These JTAG pins have weak internal pull-up P-FETs that are always enabled.
12.These pins are connected to the V_{DD}/GND planes internally and may be used by the core power supply to improve tracking and regulation.
13.Anode and cathode of internal thermal diode.
14.Treat pins AC7, T5, V2, and M7 as spare configuration pins cfg_spare[0:3]. The spare pins are unused POR config pins. It is highly recommended that the customer provide the capability of setting these pins low (that is, pull-down resistor which is not currently stuffed) in order to support new config options should they arise between revisions.
15.If this pin is connected to a device that pulls down during reset, an external pull-up is required to drive this pin to a safe state during reset.
16.This pin is only an output in FIFO mode when used as Rx flow control.
17.Do not connect.
18.These are test signals for factory use only and must be pulled up (100 Ω to 1 kΩ) to OV_{DD} for normal machine operation.
19.Independent supplies derived from board V_{DD}.
20.Recommend a pull-up resistor (1 K~) be placed on this pin to OV_{DD}.
21.The following pins must not be pulled down during power-on reset: $\overline{\text{HRESET\_REQ}}$, TRIG_OUT/READY/$\overline{\text{QUIESCE}}$, MSRCID[2:4], and ASLEEP.
22.This pin requires an external 4.7-kΩ pull-down resistor to prevent PHY from seeing a valid transmit enable before it is actively driven.
23.General-purpose POR configuration of user system.
24.When a PCI block is disabled, either the POR config pin that selects between internal and external arbiter must be pulled down to select external arbiter if there is any other PCI device connected on the PCI bus, or leave the address pins as No Connect or terminated through 2–10 kΩ pull-up resistors with the default of internal arbiter if the address pins are not connected to any other PCI device. The PCI block will drive the address pins if it is configured to be the PCI arbiter—through POR config pins—irrespective of whether it is disabled via the DEVDISR register or not. It may cause contention if there is any other PCI device connected on the bus.
25.MDIC0 is grounded through an 18.2-Ω precision 1% resistor and MDIC1 is connected GV_{DD} through an 18.2-Ω precision 1% resistor. These pins are used for automatic calibration of the DDR IOs.
26.Connect to GND.
27.Connect to GND.
28.For systems that boot from a local bus (GPCM)-controlled flash, a pull-up on LGPL4 is required.

Note that there is no default for this PLL ratio; these signals must be pulled to the desired values. Also note that the DDR data rate is the determining factor in selecting the CCB bus frequency, since the CCB frequency must equal the DDR data rate.

Table 60. CCB Clock Ratio

Binary Value of LA[28:31] Signals	CCB:SYSCLK Ratio	Binary Value of LA[28:31] Signals	CCB:SYSCLK Ratio
0000	16:1	1000	8:1
0001	Reserved	1001	9:1
0010	Reserved	1010	10:1
0011	3:1	1011	Reserved
0100	4:1	1100	12:1
0101	5:1	1101	Reserved
0110	6:1	1110	Reserved
0111	Reserved	1111	Reserved

19.3 e500 Core PLL Ratio

Table 61 describes the clock ratio between the e500 core complex bus (CCB) and the e500 core clock. This ratio is determined by the binary value of LBCTL, LALE, and LGPL2 at power up, as shown in Table 61.

Table 61. e500 Core to CCB Clock Ratio

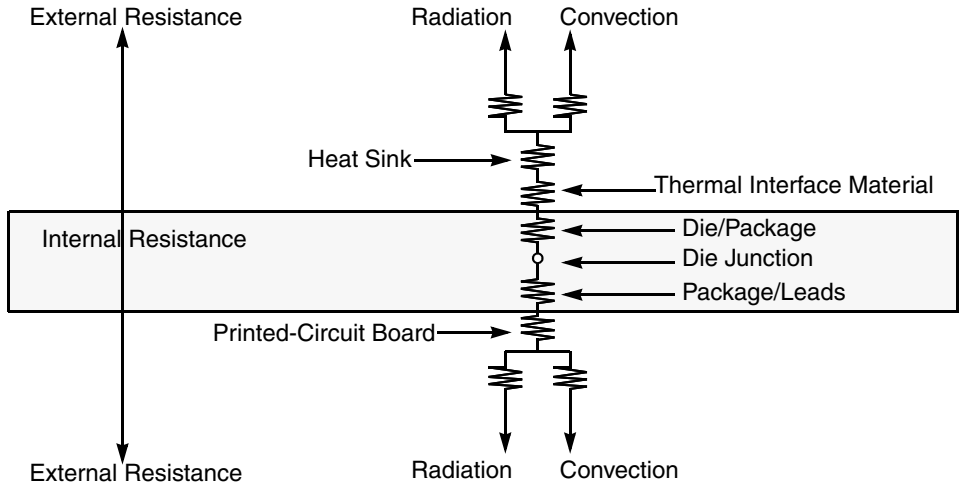
Binary Value of LBCTL, LALE, LGPL2 Signals	e500 core:CCB Clock Ratio	Binary Value of LBCTL, LALE, LGPL2 Signals	e500 core:CCB Clock Ratio
000	4:1	100	2:1
001	Reserved	101	5:2
010	Reserved	110	3:1
011	3:2	111	7:2

19.4 PCI Clocks

For specifications on the PCI_CLK, refer to the *PCI 2.2 Local Bus Specifications*.

The use of PCI_CLK is optional if SYSCLK is in the range of 33–66 MHz. If SYSCLK is outside this range then use of PCI_CLK is required as a separate PCI clock source, asynchronous with respect to SYSCLK.

Figure 58 depicts the primary heat transfer path for a package with an attached heat sink mounted to a printed-circuit board.



(Note the internal versus external package resistance.)

Figure 58. Package with Heat Sink Mounted to a Printed-Circuit Board

The heat sink removes most of the heat from the device. Heat generated on the active side of the chip is conducted through the silicon and through the heat sink attach material (or thermal interface material), and finally to the heat sink. The junction-to-case thermal resistance is low enough that the heat sink attach material and heat sink thermal resistance are the dominant terms.

20.3.2 Thermal Interface Materials

A thermal interface material is required at the package-to-heat sink interface to minimize the thermal contact resistance. For those applications where the heat sink is attached by spring clip mechanism, Figure 59 shows the thermal performance of three thin-sheet thermal-interface materials (silicone, graphite/oil, floroether oil), a bare joint, and a joint with thermal grease as a function of contact pressure. As shown, the performance of these thermal interface materials improves with increasing contact pressure. The use of thermal grease significantly reduces the interface thermal resistance. The bare joint results in a thermal resistance approximately six times greater than the thermal grease joint.